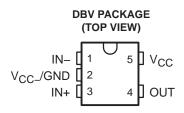
SLVS238E - AUGUST 1999 - REVISED SEPTEMBER 2004

- Single Supply or Dual Supplies
- Wide Range of Supply Voltage ... 2 V to 36 V
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.4 mA Typ
- Low Input Bias Current . . . 25 nA Typ
- Low Input Offset Voltage . . . 2 mV Typ
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS



description/ordering information

This device consists of a single voltage comparator that is designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible if the difference between the two supplies is 2 V to 36 V and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The output can be connected to other open-collector outputs to achieve wired-AND relationships.

ORDERING INFORMATION

TA	V _{IO} (max) at 25°C	PACKA	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡
-40°C to 85°C	5 mV	SOT-23 (DBV)	Reel of 3000	TL331IDBVR	T11
	SIIIV	301-23 (DBV)	Reel of 250	TL331IDBVT	' ''_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

logic diagram



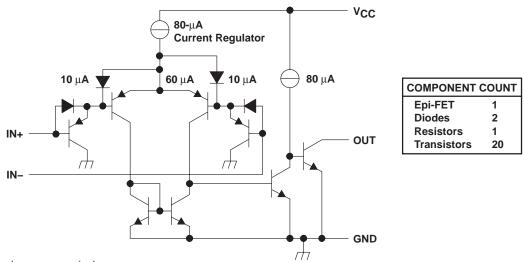


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[‡] DBV: The actual top-side marking has one additional character that designates the assembly/test site.

schematic



Current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)	36 V
Differential input voltage, V _{ID} (see Note 2)	±36 V
Input voltage range, V _I (either input)	0.3 V to 36 V
Output voltage, VO	36 V
Output current, IO	20 mA
Duration of output short-circuit to ground (see Note 3)	Unlimited
Package thermal impedance, θ _{JA} (see Notes 4 and 5)	206°C/W
Operating virtual junction temperature, T _J	150°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the network ground.
 - 2. Differential voltages are at IN+ with respect to IN-.
 - 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 - Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can impact reliability.
 - 5. The package thermal impedance is calculated in accordance with JESD 51-7.



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electrical characteristics at specified free-air temperature, $V_{CC} = 5 \text{ V}$ (unless otherwise noted)

	PARAMETER	TEST C	ONDITIONS	T _A †	MIN	TYP	MAX	UNIT	
	Lamest affact confirms	V _{CC} = 5 V to 30	V, V _O = 1.4 V,	25°C		2	5	\/	
V _{IO}	Input offset voltage	VIC = VIC(min)	_	-40°C to 85°C			9	mV	
	Name of the state	V 44V		25°C		5	50		
liO	Input offset current	$V_0 = 1.4 \text{ V}$		-40°C to 85°C			250	nA	
				25°C		-25	-250		
lΒ	Input bias current	V _O = 1.4 V		-40°C to 85°C			-400	nA	
.,	Common-mode			25°C	0 to V _{CC} – 1.5				
VICR	input voltage range‡			-40°C to 85°C	0 to V _{CC} – 1.5			V	
AVD	Large-signal differential voltage amplification	$V_{CC} = 15 \text{ V}, V_{O}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } V_{O}$	= 1.4 V to 11.4 V,	25°C	50	200		V/mV	
		V _{OH} = 5 V,	V _{ID} = 1 V	25°C		0.1	50	nA	
ЮН	High-level output current	V _{OH} = 30 V,	V _{ID} = 1 V	-40°C to 85°C			1	μΑ	
.,				25°C		150	400	.,	
VOL	Low-level output voltage	$I_{OL} = 4 \text{ mA},$	$V_{ID} = -1 V$	-40°C to 85°C			700	mV	
loL	Low-level output current	V _{OL} = 1.5 V,	V _{ID} = 1 V	25°C	6			mA	
Icc	Supply current	R _L = ∞,	V _{CC} = 5 V	25°C		0.4	0.7	mA	

[†] All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CON	TYP	UNIT	
R _L connected to 5 V through 5.1 kΩ,	R _L connected to 5 V through 5.1 kΩ,	100-mV input step with 5-mV overdrive	1.3	
Response time	C _L = 15 pF§ (see Note 6)	TTL-level input step	0.3	μs

[§] C_L includes probe and jig capacitance.

NOTE 6: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



[‡] The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V, but either or both inputs can go to 30 V without damage.





i.com 29-May-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TL331IDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVRE4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TL331IDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

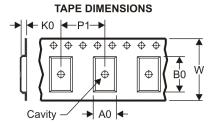
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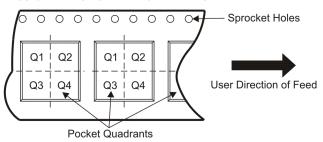
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

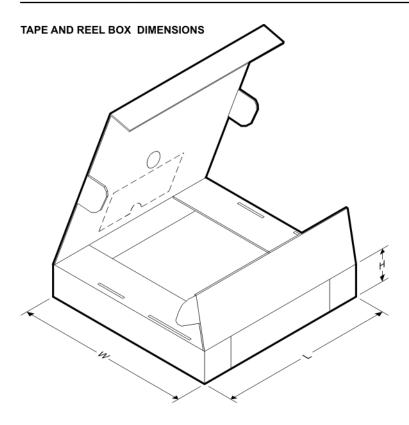
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL331IDBVR	SOT-23	DBV	5	3000	180.0	9.2	3.23	3.17	1.37	4.0	8.0	Q3
TL331IDBVT	SOT-23	DBV	5	250	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL331IDBVR	SOT-23	DBV	5	3000	202.0	201.0	28.0
TL331IDBVT	SOT-23	DBV	5	250	195.0	200.0	45.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.



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